

## Dual Enhancement Mode MOSFET (N- and P-Channel)

### Features

- N-Channel  
30V/7A,  
 $R_{DS(ON)} = 20m\Omega$  (typ.) @  $V_{GS} = 10V$   
 $R_{DS(ON)} = 30m\Omega$  (typ.) @  $V_{GS} = 4.5V$
- P-Channel  
-30V/-5A,  
 $R_{DS(ON)} = 40m\Omega$  (typ.) @  $V_{GS} = -10V$   
 $R_{DS(ON)} = 62m\Omega$  (typ.) @  $V_{GS} = -4.5V$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

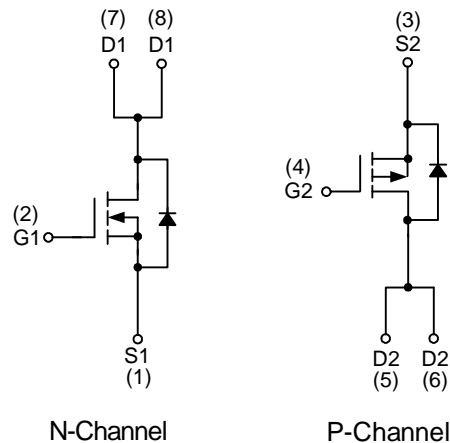
### Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems

### Pin Description



Top View of SOP – 8



### Ordering and Marking Information

<p>APM4550 <span style="border: 1px solid black; padding: 2px;">□□-□□□</span></p> <p style="margin-left: 20px;"> <span style="border: 1px solid black; padding: 2px;">□□</span> : Lead Free Code  <span style="border: 1px solid black; padding: 2px;">□□</span> : Handling Code  <span style="border: 1px solid black; padding: 2px;">□</span> : Temp. Range  <span style="border: 1px solid black; padding: 2px;">□</span> : Package Code         </p>	<p>Package Code K : SOP-8</p> <p>Operating Junction Temp. Range C : -55 to 150°C</p> <p>Handling Code TR : Tape &amp; Reel      TU : Tube</p> <p>Lead Free Code L : Lead Free Device</p>
<p>APM4550K : <span style="border: 1px solid black; padding: 2px; display: inline-block; text-align: center;">APM4550 XXXXX</span></p>	<p>XXXXXX - Date Code</p>

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte in plate termination finish; which are fully compliant with RoHS and compatible with both SnPb and lead-free soldering operations. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J STD-020C for MSL classification at lead-free peak reflow temperature.

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

## Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	N Channel	P Channel	Unit
$V_{DSS}$	Drain-Source Voltage	30	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	
$I_D^*$	Continuous Drain Current	7	-5	A
$I_{DM}^*$	300 $\mu\text{s}$ Pulsed Drain Current			
$I_S^*$	Diode Continuous Forward Current	2.5	-2	A
$T_J$	Maximum Junction Temperature	150		$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150		
$P_D^*$	Power Dissipation	$T_A=25^\circ\text{C}$	2	W
		$T_A=100^\circ\text{C}$	0.8	
$R_{\theta JA}^*$	Thermal Resistance-Junction to Ambient	62.5		$^\circ\text{C}/\text{W}$

Note: \*Surface Mounted on 1in<sup>2</sup> pad area,  $t \leq 10\text{sec}$ .

## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	APM4550K			Unit	
			Min.	Typ.	Max.		
<b>Static Characteristics</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$	N-Ch	30		V	
		$V_{GS}=0\text{V}, I_{DS}=-250\mu\text{A}$	P-Ch	-30			
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$	N-Ch		1	$\mu\text{A}$	
					30		
		$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$	P-Ch		-1		
					-30		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	N-Ch	1	1.5	2	V
		$V_{DS}=V_{GS}, I_{DS}=-250\mu\text{A}$	P-Ch	-1	-1.5	-2	
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	N-Ch			$\pm 100$	nA
			P-Ch			$\pm 100$	
$R_{DS(ON)}^a$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_{DS}=7\text{A}$	N-Ch		20	27.5	m $\Omega$
		$V_{GS}=-10\text{V}, I_{DS}=-5\text{A}$	P-Ch		40	50	
		$V_{GS}=4.5\text{V}, I_{DS}=5\text{A}$	N-Ch		30	40	
		$V_{GS}=-4.5\text{V}, I_{DS}=-4\text{A}$	P-Ch		62	80	

## Electrical Characteristics (Cont.) (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	APM4550K			Unit	
			Min.	Typ.	Max.		
<b>Diode Characteristics</b>							
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> =2.5A, V <sub>GS</sub> =0V	N-Ch		0.8	1.3	V
		I <sub>SD</sub> =-2A, V <sub>GS</sub> =0V	P-Ch		-0.8	-1.3	
t <sub>rr</sub>	Reverse Recovery Time	N-Channel I <sub>SD</sub> =7A, dI <sub>SD</sub> /dt=100A/μs	N-Ch		8		ns
			P-Ch		13		
Q <sub>rr</sub>	Reverse Recovery Charge	N-Channel I <sub>SD</sub> =-5A, dI <sub>SD</sub> /dt=100A/μs	N-Ch		3		nC
			P-Ch		5		
<b>Dynamic Characteristics<sup>b</sup></b>							
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	N-Ch		2		Ω
			P-Ch		8.3		
C <sub>iss</sub>	Input Capacitance	N-Channel V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, Frequency=1.0MHz	N-Ch		620		pF
C <sub>oss</sub>	Output Capacitance	P-Channel V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, Frequency=1.0MHz	P-Ch		590		
			N-Ch		85		
C <sub>rss</sub>	Reverse Transfer Capacitance	P-Channel V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, Frequency=1.0MHz	P-Ch		95		
			N-Ch		65		
t <sub>d(ON)</sub>	Turn-on Delay Time	N-Channel V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω, I <sub>DS</sub> =1A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω	N-Ch		6	11	ns
			P-Ch		5	9	
T <sub>r</sub>	Turn-on Rise Time	P-Channel V <sub>DD</sub> =-15V, R <sub>L</sub> =15Ω, I <sub>DS</sub> =-1A, V <sub>GEN</sub> =-10V, R <sub>G</sub> =6Ω	N-Ch		10	18	
			P-Ch		12	23	
t <sub>d(OFF)</sub>	Turn-off Delay Time	N-Channel V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω, I <sub>DS</sub> =1A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω	N-Ch		22	41	
			P-Ch		27	50	
T <sub>f</sub>	Turn-off Fall Time	P-Channel V <sub>DD</sub> =-15V, R <sub>L</sub> =15Ω, I <sub>DS</sub> =-1A, V <sub>GEN</sub> =-10V, R <sub>G</sub> =6Ω	N-Ch		3	6	
			P-Ch		13	24	
<b>Gate Charge Characteristics<sup>b</sup></b>							
Q <sub>g</sub>	Total Gate Charge	N-Channel V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>DS</sub> =7A	N-Ch		14	19	nC
			P-Ch		11	15	
Q <sub>gs</sub>	Gate-Source Charge	P-Channel V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>DS</sub> =-5A	N-Ch		1.4		
			P-Ch		1.3		
Q <sub>gd</sub>	Gate-Drain Charge	N-Channel V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>DS</sub> =7A	N-Ch		2.6		
			P-Ch		2.7		

**Notes:**

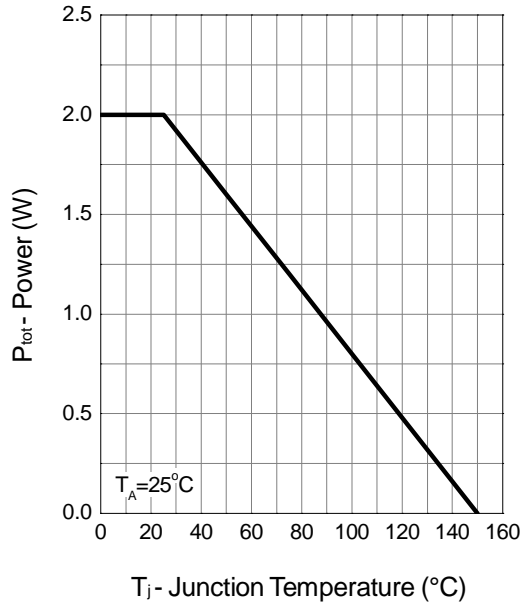
a : Pulse test ; pulse width ≤300μs, duty cycle ≤ 2%.

b : Guaranteed by design, not subject to production testing.

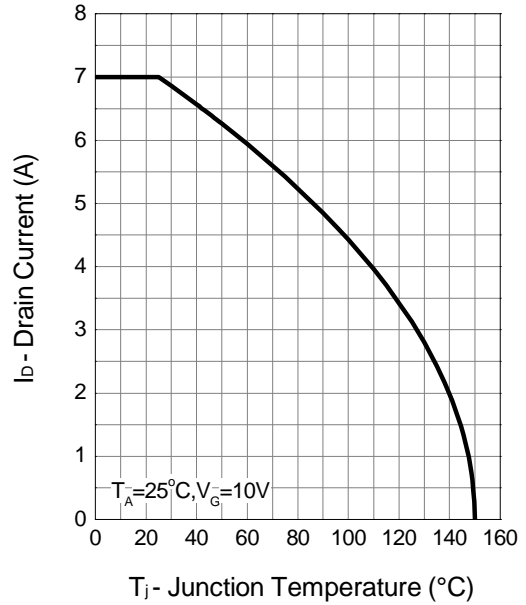
## Typical Characteristics

### N-Channel

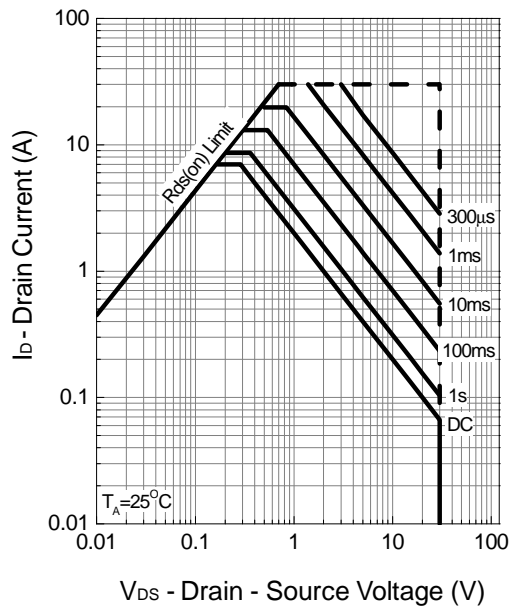
Power Dissipation



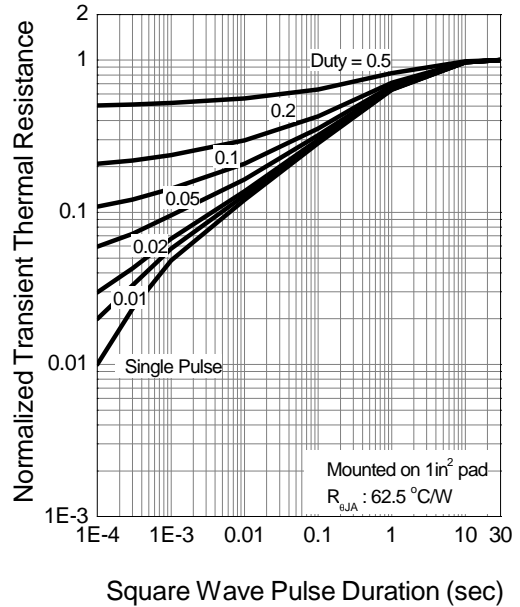
Drain Current



Safe Operation Area



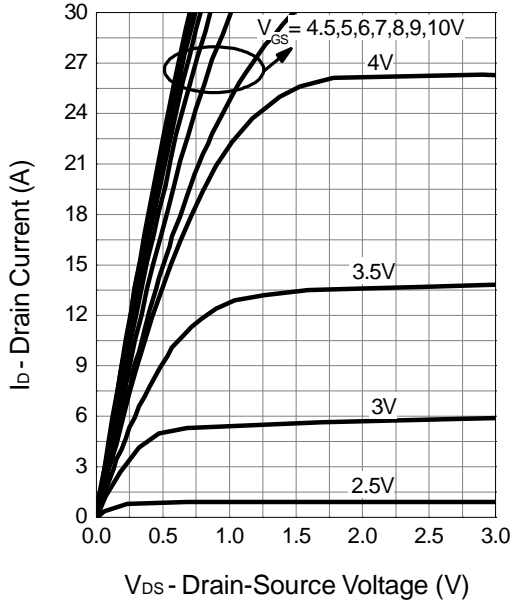
Thermal Transient Impedance



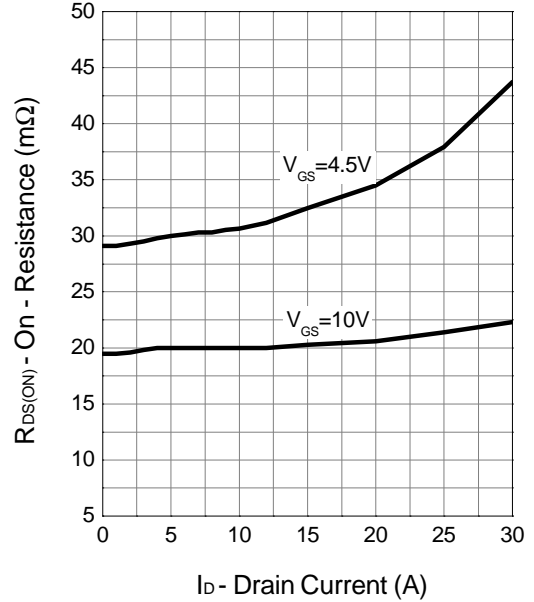
## Typical Characteristics (Cont.)

### N-Channel

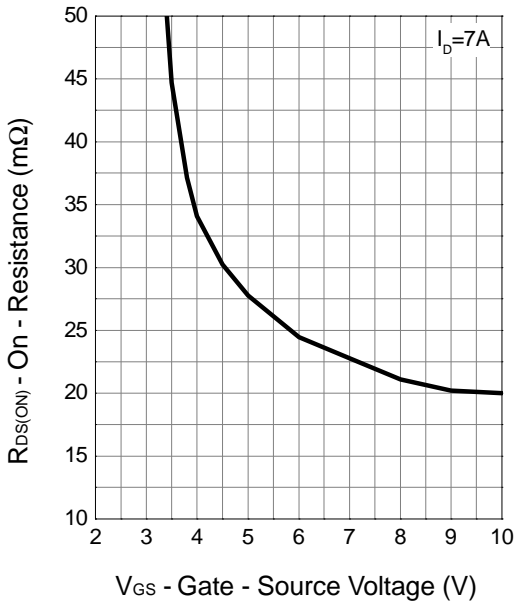
Output Characteristics



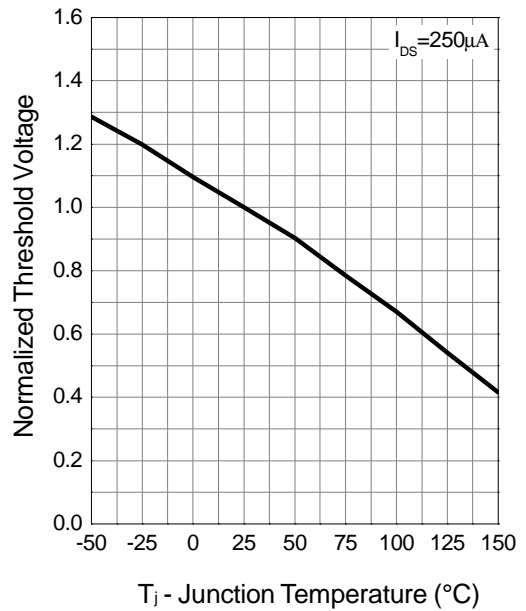
Drain-Source On Resistance



Drain-Source On Resistance



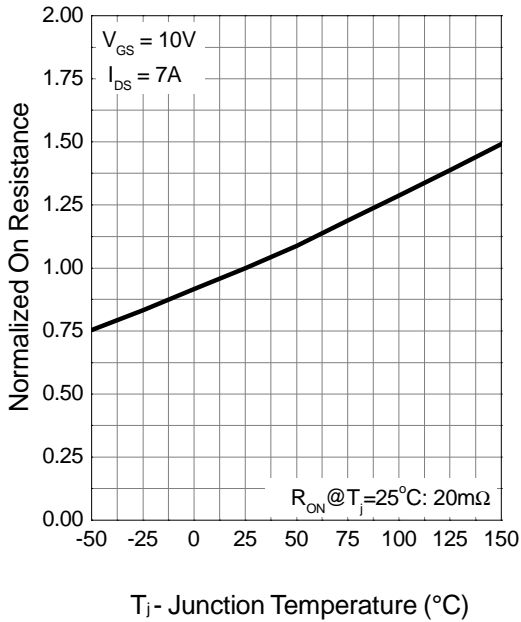
Gate Threshold Voltage



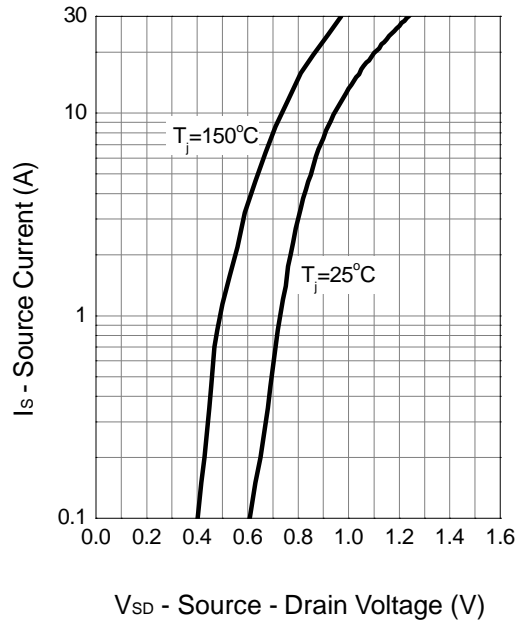
Typical Characteristics (Cont.)

N-Channel

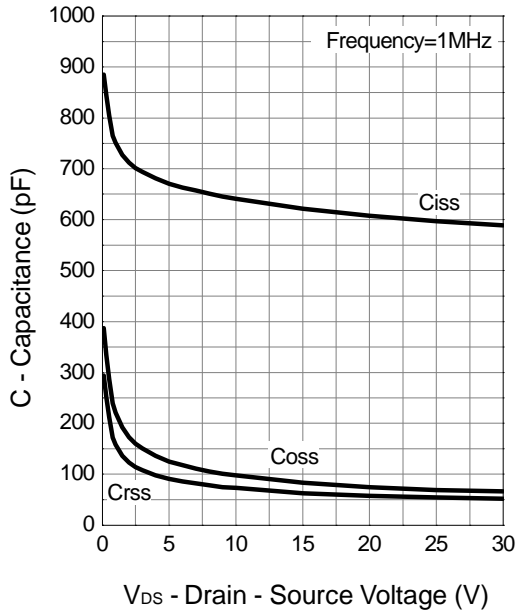
Drain-Source On Resistance



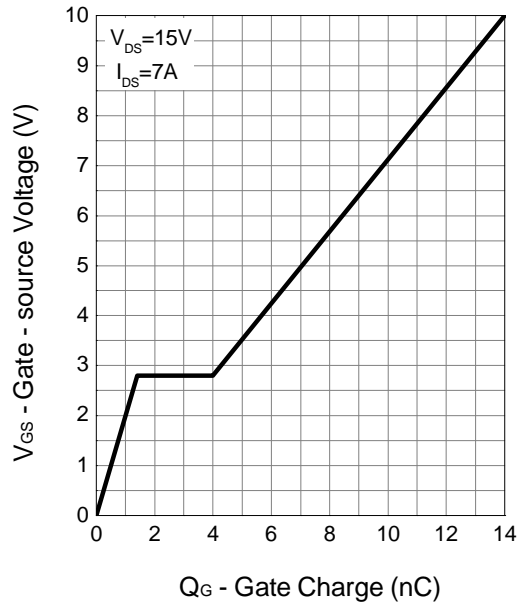
Source-Drain Diode Forward



Capacitance



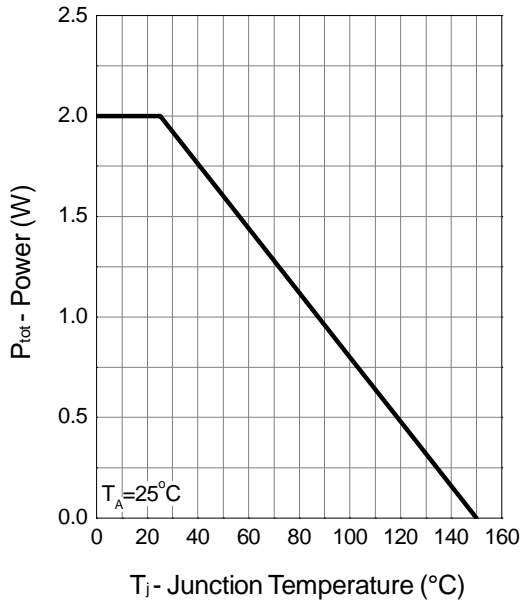
Gate Charge



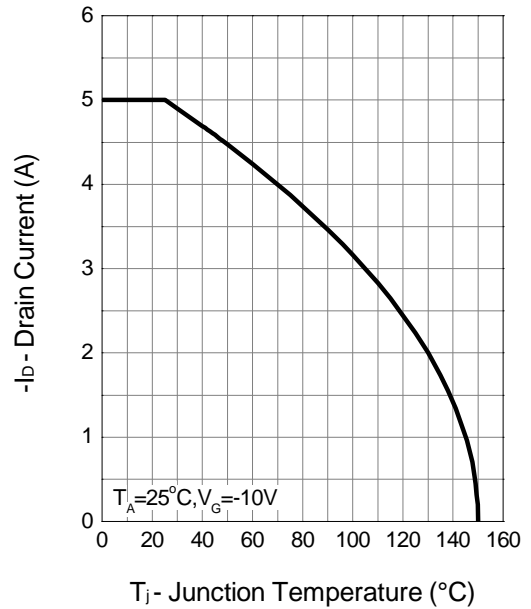
## Typical Characteristics (Cont.)

### P-Channel

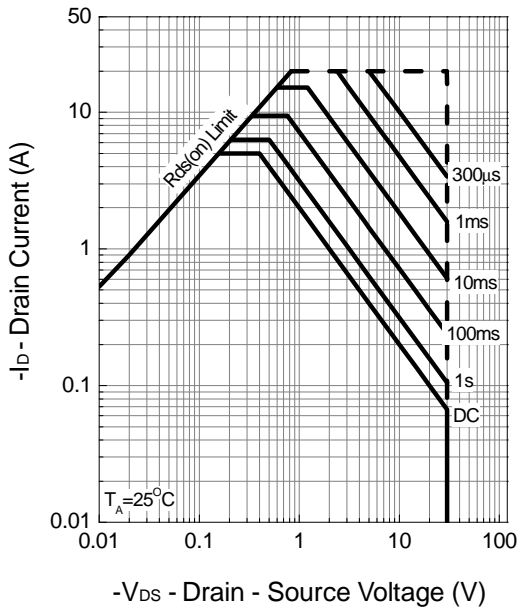
Power Dissipation



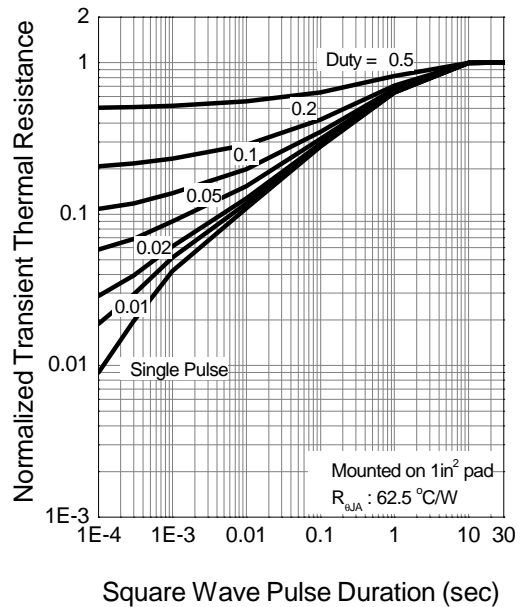
Drain Current



Safe Operation Area



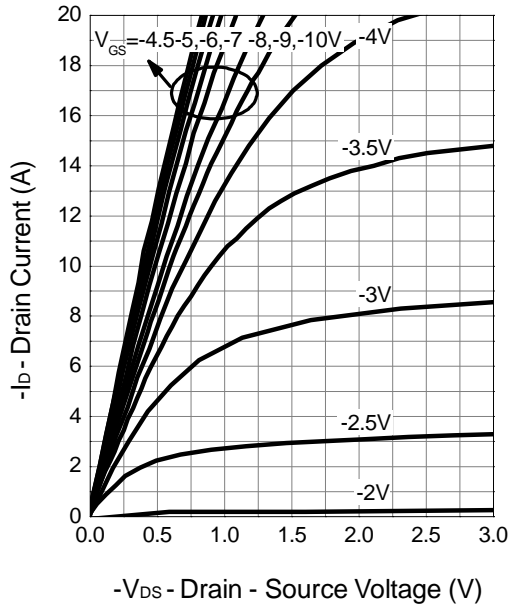
Thermal Transient Impedance



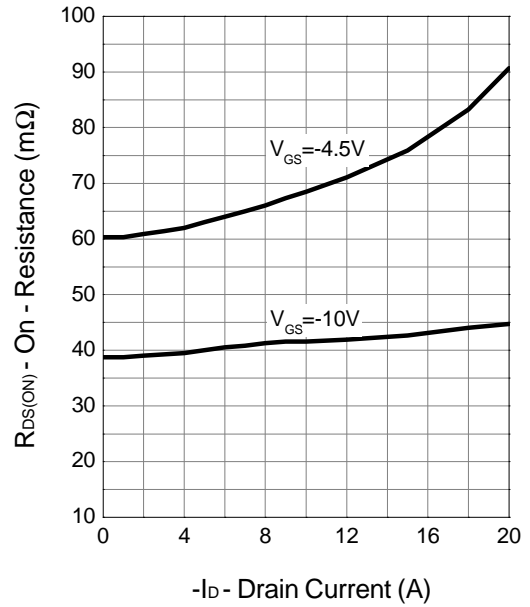
## Typical Characteristics (Cont.)

### P-Channel

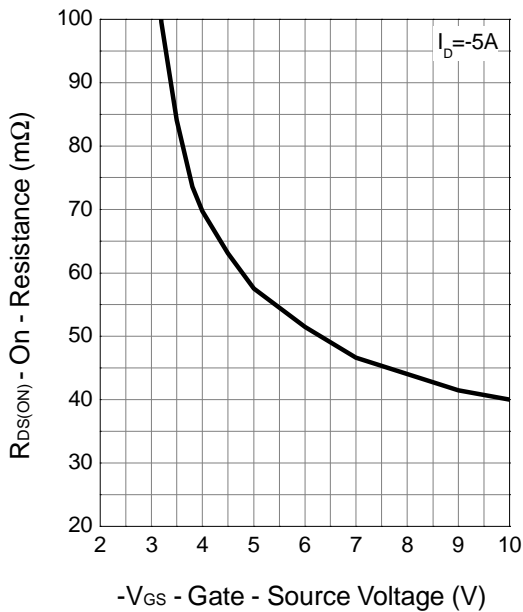
Output Characteristics



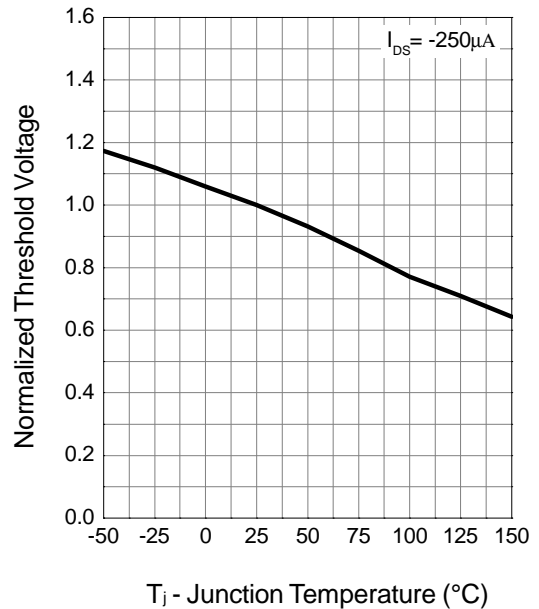
Drain-Source On Resistance



Drain-Source On Resistance



Gate Threshold Voltage

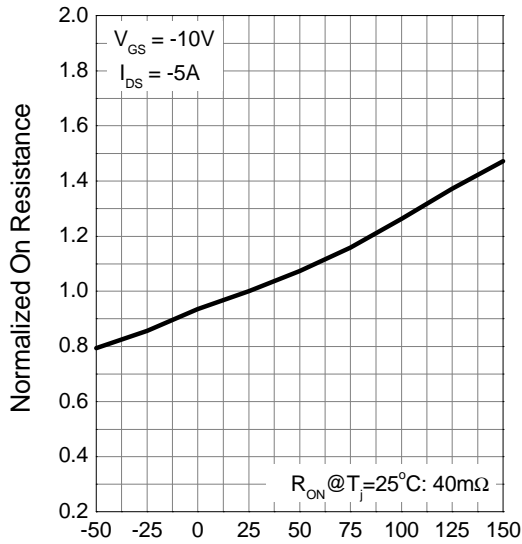




Typical Characteristics (Cont.)

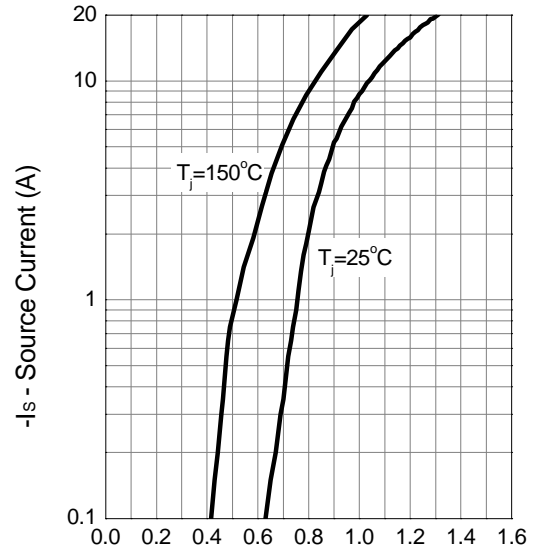
P-Channel

Drain-Source On Resistance



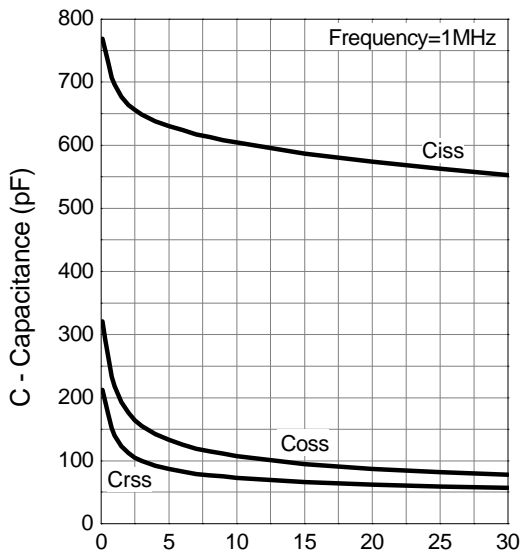
T<sub>j</sub> - Junction Temperature (°C)

Source-Drain Diode Forward



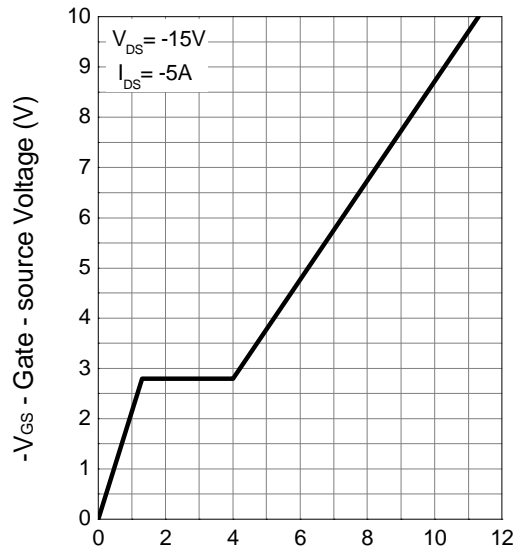
-V<sub>SD</sub> - Source - Drain Voltage (V)

Capacitance



-V<sub>DS</sub> - Drain - Source Voltage (V)

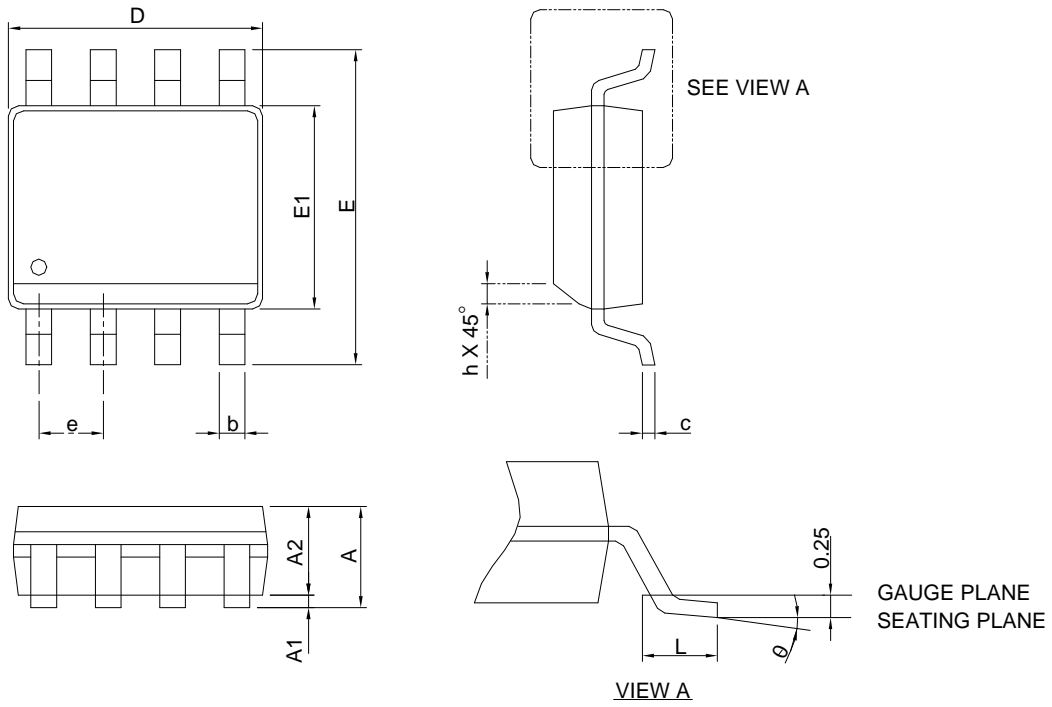
Gate Charge



Q<sub>G</sub> - Gate Charge (nC)

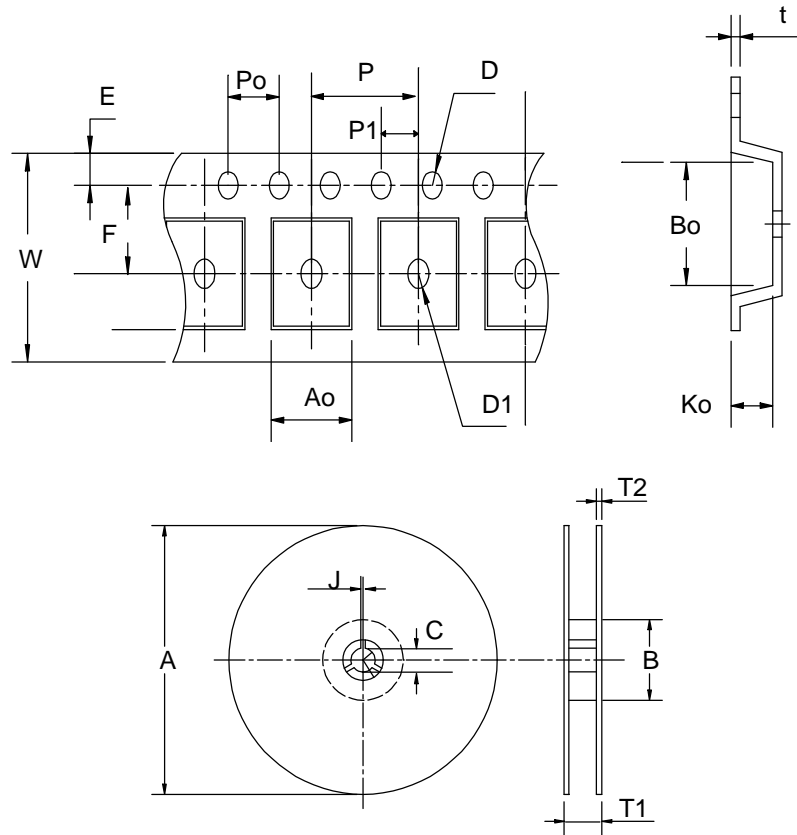
Package Information

SOP-8



SYMBOL	SOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.75		0.069
A1	0.10	0.25	0.004	0.010
A2	1.25		0.049	
b	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.90 BSC		0.193 BSC	
E	6.00 BSC		0.236 BSC	
E1	3.90 BSC		0.154 BSC	
e	1.00 BSC		0.050 BSC	
h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

### Carrier Tape & Reel Dimensions



Application	A	B	C	J	T1	T2	W	P	E
SOP-8	330±1	62 ± 1.5	12.75 + 0.15	2 + 0.5	12.4 +0.2	2± 0.2	12 + 0.3 - 0.1	8± 0.1	1.75± 0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5 ± 0.1	1.55±0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013

(mm)

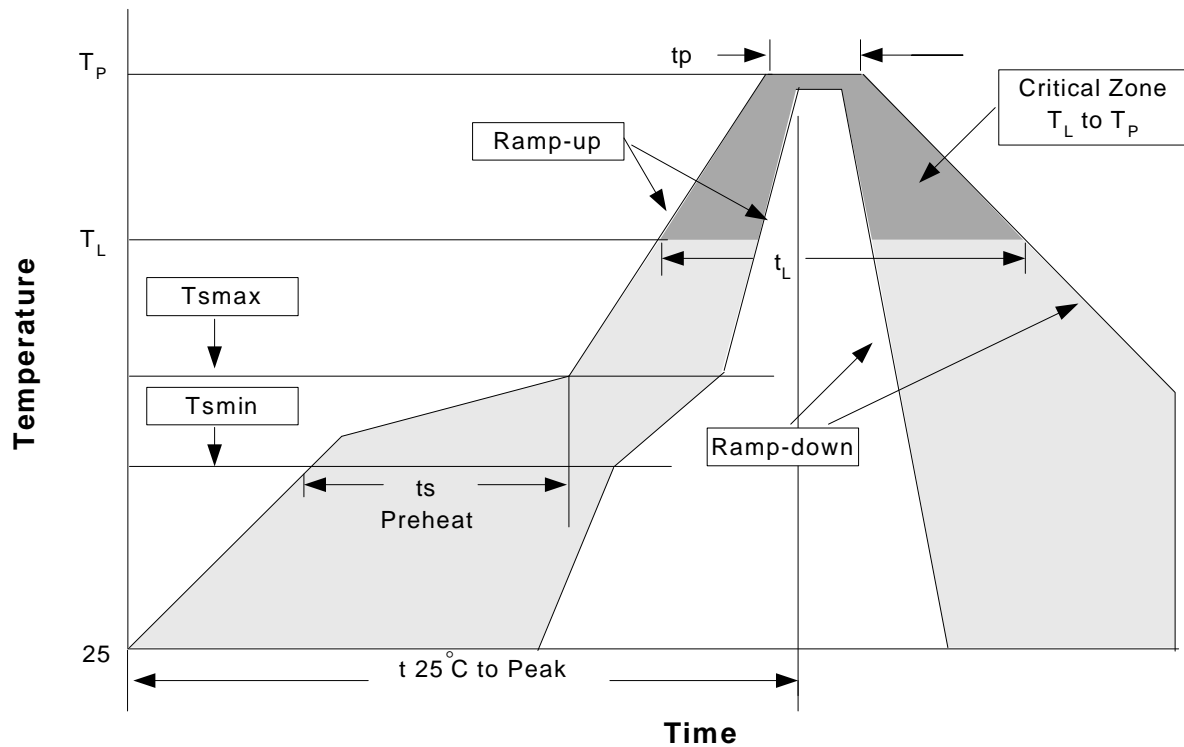
### Devices Per Reel

Package Type	Devices Per Reel
SOP- 8	2500

## Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb), 100%Sn
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

### Reflow Condition (IR/Convection or VPR Reflow)



### Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min ( $T_{smin}$ )	100°C	150°C
- Temperature Max ( $T_{smax}$ )	150°C	200°C
- Time (min to max) ( $t_s$ )	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature ( $T_L$ )	183°C	217°C
- Time ( $t_L$ )	60-150 seconds	60-150 seconds
Peak/Classification Temperature ( $T_p$ )	See table 1	See table 2
Time within 5°C of actual Peak Temperature ( $t_p$ )	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Notes: All temperatures refer to topside of the package. Measured on the body surface.

## Classification Reflow Profiles (Cont.)

Table 1. SnPb Eutectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≈350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 2. Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 +0°C*	260 +0°C*	260 +0°C*
1.6 mm – 2.5 mm	260 +0°C*	250 +0°C*	245 +0°C*
≥2.5 mm	250 +0°C*	245 +0°C*	245 +0°C*

\* Tolerance: The device manufacturer/supplier **shall** assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C) at the rated MSL level.

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 SEC
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @125°C
PCT	JESD-22-B,A102	168 Hrs, 100%RH, 121°C
TST	MIL-STD-883D-1011.9	-65°C~150°C, 200 Cycles
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> > 100mA

## Customer Service

### Anpec Electronics Corp.

Head Office :

No.6, Dusing 1st Road, SBIP,

Hsin-Chu, Taiwan, R.O.C.

Tel : 886-3-5642000

Fax : 886-3-5642050

Taipei Branch :

7F, No. 137, Lane 235, Pao Chiao Rd.,

Hsin Tien City, Taipei Hsien, Taiwan, R. O. C.

Tel : 886-2-89191368

Fax : 886-2-89191369